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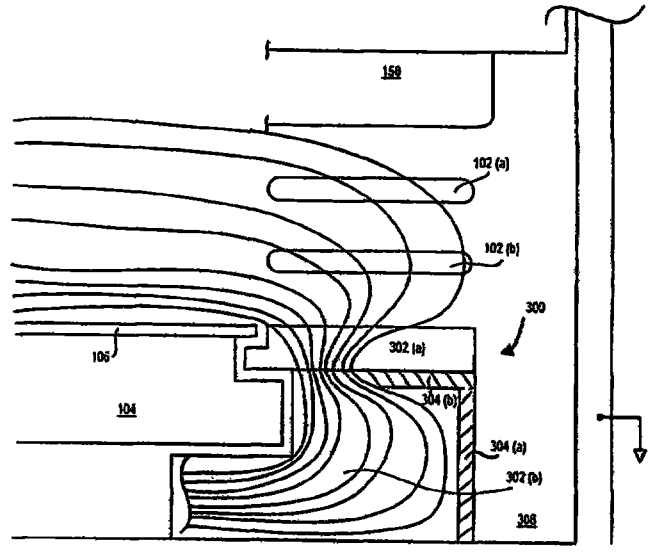
(54) Title: FOCUS RING ARRANGEMENT FOR SUBSTANTIALLY ELIMINATING UNCONFINED PLASMA IN A PLASMA PROCESSING CHAMBER

(57) Abstract

A focus ring assembly configured to substantially encircle a chuck of a plasma processing chamber. The focus ring assembly includes an annular dielectric body; and an electrically conductive shield surrounding the annular dielectric body. The electrically conductive shield is configured to be electrically grounded within the plasma processing chamber and includes a tube–shaped portion being disposed outside of the annular dielectric body and surrounding at least part of the annular dielectric body. The electrically conductive shield further includes an inwardly–protruding flange portion being in electrical contact with the tube–shaped portion. The flange portion forms a plane that intersects the tube–shaped portion. The flange portion is embedded within the annular dielectric body.



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